

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Cancelled)

2. (Currently Amended) A module component comprising:

a substrate

a partition formed on the substrate, the partition having a predetermined height to divide the substrate into a plurality of circuit blocks;

a first sealing member covering a first circuit block of the plurality of circuit blocks;

a second sealing member covering a second circuit block of the plurality of circuit blocks;

a first conductive film covering at least a surface of the first sealing member and being continuous from the partition to the substrate; and

a second conductive film covering at least a surface of the second sealing member and being continuous from the partition to the substrate;

the plurality of circuit blocks are electrically shielded individually and the partition is made of a composition of a resin and an electrically conductive material;The module component according to claim 1, wherein

the substrate is made of resin; and

the first sealing member, the second sealing member and the partition contain a same resin.

3. (Currently Amended) A module component comprising:

a substrate

a partition formed on the substrate, the partition having a predetermined height to divide the substrate into a plurality of circuit blocks;

a first sealing member covering a first circuit block of the plurality of circuit blocks;

a second sealing member covering a second circuit block of the plurality of circuit blocks;

a first conductive film covering at least a surface of the first sealing member and being continuous from the partition to the substrate; and

a second conductive film covering at least a surface of the second sealing member and being continuous from the partition to the substrate;

the plurality of circuit blocks are electrically shielded individually and the partition is made of a composition of a resin and an electrically conductive material;~~The module component according to claim 1, wherein~~

the substrate is ceramic;

the composition is made of ceramic powder-containing resin and conductive material;  
and

the first sealing member, the second sealing member and the partition contain a same resin.

4. (Cancelled)

5. (Original) The module component according to claim 2, wherein the conductive material of the partition is a conductive resin.

6. (Currently Amended) The module component according to ~~claim 1~~claims 2 or 3, wherein the partition is resin having a metal film formed on an outer surface thereof, and has a square cross section in a longitudinal direction.

7. (Cancelled)

8. (Currently Amended) The module component according to ~~claim 1~~claims 2 or 3, wherein the partition has a conductive wall in a direction vertical to the substrate.

9. (Cancelled)

10. (Currently Amended) The module component according to ~~claim 1~~claims 2 or 3, wherein the partition has resin at least one side surface thereof.

11. (Currently Amended) The module component according to ~~claim 1~~claims 2 or 3, wherein the partition is positioned inside the substrate, and has a planar shape of one of a circle and a polygon.

12. (Original) The module component according to claim 11, wherein the partition is positioned out of contact with an outer edge of the substrate.

13. (Currently Amended) The module component according to ~~claim 1~~claims 2 or 3, wherein the partition has a planar shape of a letter T.

14. (Currently Amended) The module component according to ~~claim 1~~claims 2 or 3, wherein either a) the first conductive film and the second conductive film include metal or b) the first conductive film and the second conductive film include conductive resin.

15. (Currently Amended) The module component according to ~~claim 1~~claims 2 or 3, wherein the partition is higher than an electric component mounted on the substrate.

16. (Currently Amended) The module component according to ~~claim 1~~claims 2 or 3, wherein the substrate has a ground pattern on a surface thereof, and the ground pattern is connected with the first conductive film and the second conductive film.

17. - 27. (Cancelled)